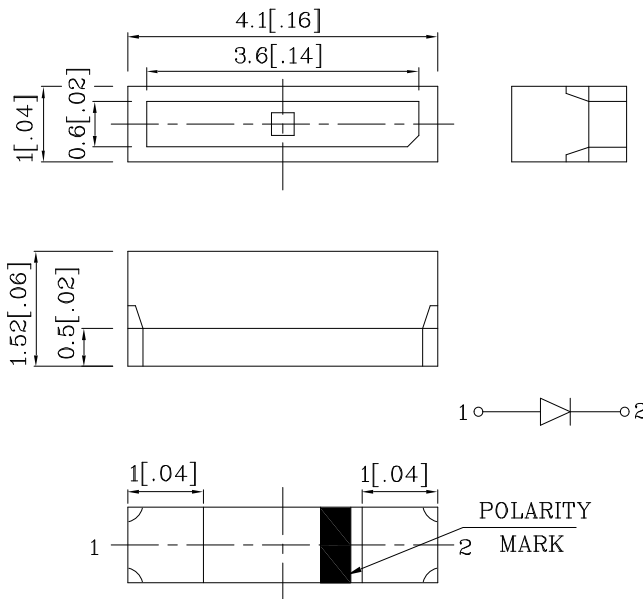


PRELIMINARY SPEC

Features

- 4.1mm x 1.0mm RIGHT ANGLE SMT LED, 1.52mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS/REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



ATTENTION
 OBSERVE PRECAUTIONS
 FOR HANDLING
 ELECTROSTATIC
 DISCHARGE
 SENSITIVE
 DEVICES

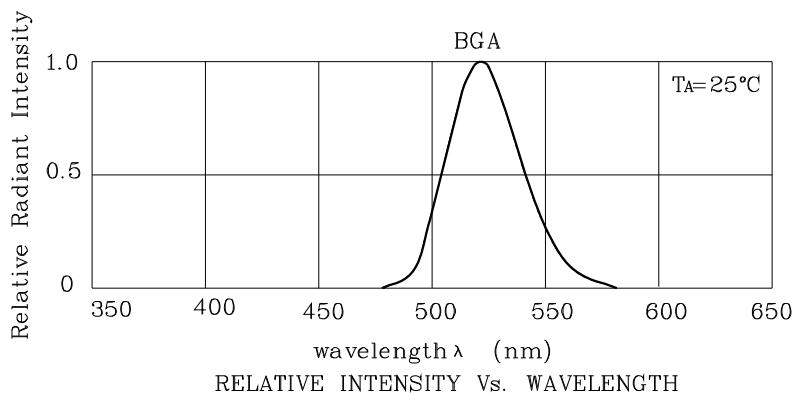
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

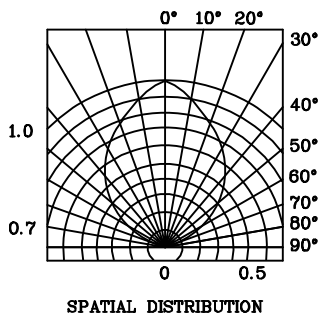
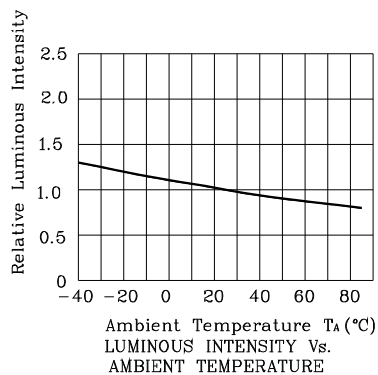
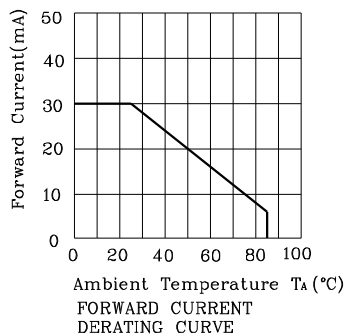
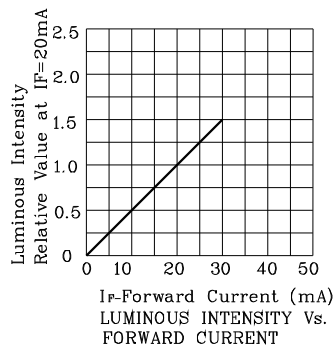
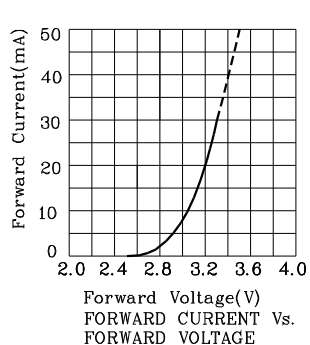
Absolute Maximum Ratings (TA=25°C)		BGA (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA
Power Dissipation	P _T	120	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

Operating Characteristics (TA=25°C)		BGA (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	3.2	V
Forward Voltage (Max.) (I _F =20mA)	V _F	4.0	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength Of Peak Emission (Typ.) (I _F =20mA)	λ _P	520	nm
Wavelength Of Dominant Emission (Typ.) (I _F =20mA)	λ _D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	100	pF

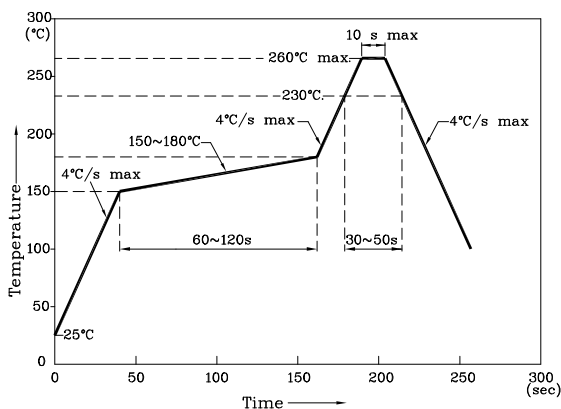
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA)		Wavelength nm λ _P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZBGA90W	Green	InGaN	Water Clear	70	198	520	90°
Published Date : JAN 23,2008 Drawing No :XDSA9833 V2 Checked : B.L.LIU P. 1/4							



❖ BGA



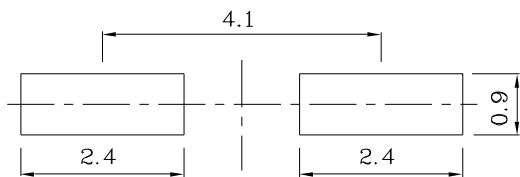
Reflow Soldering Profile For Lead-free SMT Process.



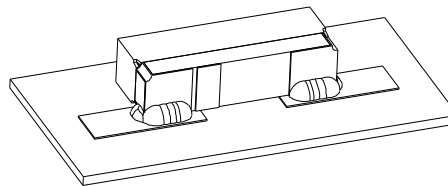
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C–260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

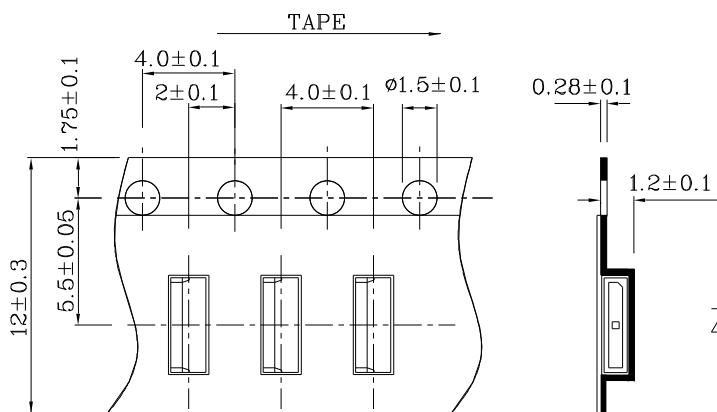
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

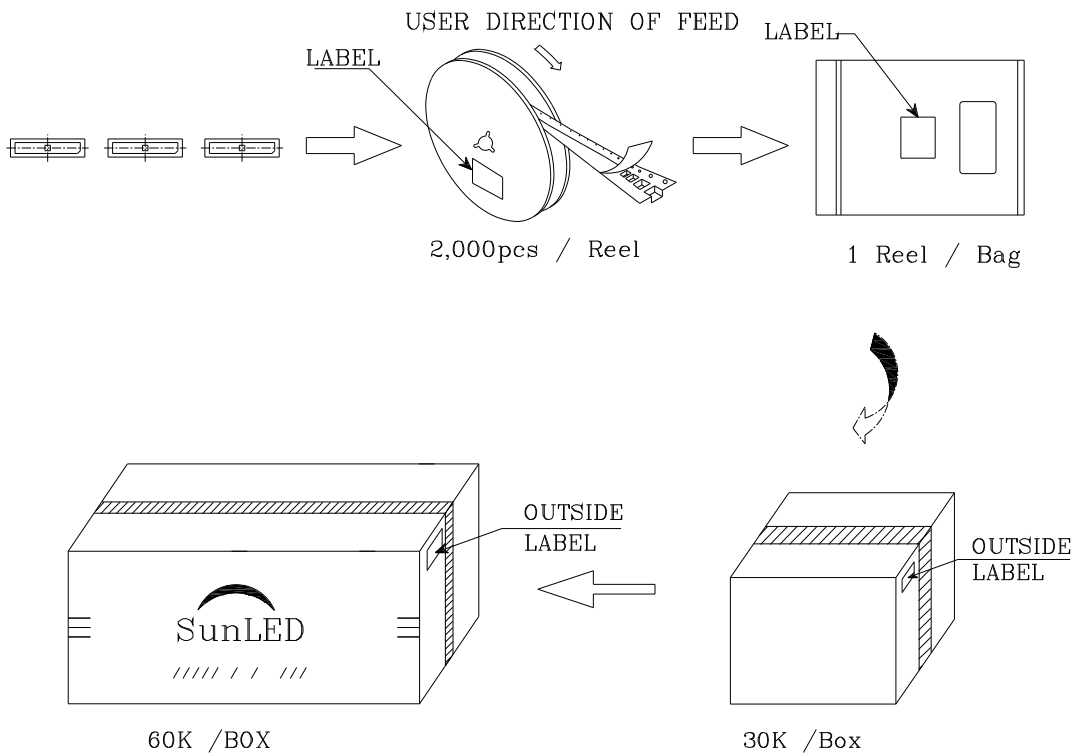

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

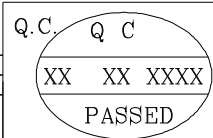

1. Wavelength: +/-1nm
2. Luminous Intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZBGA90W

	
P/NO : XZxx90x	
QTY : 2,000pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	